



THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Zuniga-Ortiz, et al.

Docket No.: TI-33986

Serial No.: 10/057,138

Art Unit: 2827

Filed: 01/25/02

Examiner: Thai, Luan C.

Title: Flip-Chip Without Bumps and Polymer for Board Assembly

Commissioner for Patents

P.O. Box 1450

Alexandria, Virginia 22313-1450

REPLY TO OFFICE ACTION MAILED JULY 16, 2003

Dear Sir:

In response to the Examiner's Office Action mailed July 16, 2003, the period for response being extended to January 16, 2004, by the concurrently filed Petition for Automatic Extension of Time, please amend this application as follows.

Date of Deposit: 12/30/2003
I hereby certify under 37 CFR 1.8(a) that this correspondence is being deposited with the United States Postal Service as **first class mail** with sufficient postage on the date indicated above and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450.
Indranil Chowdhury
Indranil Chowdhury